

Application No.: 09884,844
Amendment dated: September 3, 2004
Reply to Office Action of June 4, 2004
Attorney Docket No.:1066us

This listing of claims will replace all prior versions and listings of claims in this application:

a.) Listing of Claims

1. (currently amended) An optoelectronic hermetic package, comprising:
a frame defining a hermetic boundary; and
an electrical feedthrough assembly on the frame 1) providing electrical connections between signal wire bond areas within the hermetic boundary and electrical contact areas outside the hermetic boundary and 2) ground wire bond areas within the hermetic boundary that are electrically connected to each other.
2. (original) A package as claimed in claim 1, further comprising an array of leads extending from electrical contact areas away from the frame.
3. (original) A package as claimed in claim 2, wherein the leads extend laterally relative to the frame.
4. (currently amended) A package as claimed in claim 2, wherein the leads are pins that extend vertically relative to the frame.
5. (original) A package as claimed in claim 1, wherein at least some of the ground wire bond areas are located between two of the signal wire bond areas on the feedthrough assembly.
6. (original) A package as claimed in claim 1, wherein the ground wire bond areas are interdigitated with signal wire bond areas.
7. (original) A package as claimed in claim 1, further comprising conductive plugs extending between a top of the feedthrough assembly and the frame, the ground wire bond areas being located on a top of the conductive plugs.

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8. (original) A package as claimed in claim 1, wherein the assembly provides electrical connections between the ground wire bond areas and the frame.
9. (original) A package as claimed in claim 1, further comprising conductive plugs extending between a top of the feedthrough assembly and a bus through the assembly, the ground wire bond areas being located on a top of the conductive plugs.